

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|--|------------------|---------|------------------|
| L1 | 1 | @pn="4016593" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/04/12 12:19 |
| L2 | 7 | ("4016593").URPN. | USPAT | OR | ON | 2005/04/12 14:24 |
| S1 | 3 | (semiconductor adj wafer) and (chip adj forming adj section) | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 11:30 |
| S2 | 1651 | (semiconductor adj wafer) and (plurality multiple) adj chip | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 11:30 |
| S3 | 252 | S2 and electrode and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 11:30 |
| S4 | 45 | S3 and (hole near12 electrode) | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 14:49 |
| S5 | 3964 | hole adj electrode | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 11:43 |
| S6 | 1000 | through adj hole adj electrode | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 11:43 |
| S7 | 559 | S6 and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 12:05 |
| S8 | 17 | S7 and semiconductor adj wafer | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 11:44 |

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| S9 | 16 | S3 and (through adj hole near12 electrode) | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 12:04 |
| S10 | 16 | S9 and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 13:18 |
| S11 | 341 | semiconductor and "second through hole" and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 13:32 |
| S12 | 72 | S11 and ((through adj hole) near5 electrode) | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 13:35 |
| S13 | 2 | "4696885".pn. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 13:38 |
| S14 | 2 | "5918113".pn. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 13:45 |
| S15 | 2 | "6114192".pn. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 13:47 |
| S16 | 2 | "6333564".pn. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 13:52 |
| S17 | 2 | "6358762".pn. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 13:53 |
| S18 | 2 | "6358836".pn. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 14:06 |

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| S19 | 19 | "6388313" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 14:06 |
| S20 | 2 | "6388313".pn. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 14:11 |
| S25 | 795 | third adj through adj hole | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 15:01 |
| S26 | 17 | S25 and "438"/\$.ccls. and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 16:33 |
| S27 | 121 | ((through adj hole) near3 electrode) and (second adj through adj hole)and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 16:35 |
| S28 | 31 | S27 and (third adj through adj hole) | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/23 16:35 |
| S29 | 788 | 438/629.ccls. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 08:43 |
| S30 | 379 | 438/629.ccls. and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 09:02 |
| S31 | 106 | (etch near3 (hole via) near3 electrode) and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 09:40 |
| S32 | 1053 | 438/637.ccls. and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 09:37 |

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| S33 | 328 | 438/638.ccls. and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 10:51 |
| S34 | 362 | 438/639.ccls. and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 14:27 |
| S35 | 128 | 438/667.ccls. and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 14:32 |
| S36 | 998 | 257/774.ccls. and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 14:32 |
| S37 | 1659 | (semiconductor adj wafer) and (plurality multiple) adj chip | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 14:49 |
| S38 | 252 | S37 and electrode and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 15:28 |
| S39 | 26 | S38 and ((hole via) near2 electrode) | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 14:50 |
| S40 | 111 | S37 and ((hole via) near2 electrode) | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 14:54 |
| S41 | 30 | S40 and (second near2 (hole via)) | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 14:54 |
| S42 | 26 | S40 and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 15:35 |

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| S43 | 4 | S41 and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 15:35 |
| S44 | 21 | ((hole via) adj electrode) and dielectric adj electrode | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 15:52 |
| S46 | 13 | S44 and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 15:51 |
| S47 | 3 | ((hole via) adj electrode) and dielectric adj over adj electrode | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 15:54 |
| S48 | 6 | ((hole via) near2 electrode) and dielectric adj over adj electrode | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/25 16:49 |
| S49 | 4 | S48 and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 15:56 |
| S51 | 2 | "6252266".pn. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 16:30 |
| S52 | 35 | hoshi.in. and mitsubishi.as. | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/24 16:33 |
| S53 | 287 | hoshi.in. and mitsubishi.as. | JPO | OR | ON | 2005/03/24 16:33 |
| S56 | 4 | S53 and transistor | JPO | OR | ON | 2005/03/25 08:19 |
| S58 | 1 | JP409153516A | JPO | OR | ON | 2005/03/25 14:11 |
| S60 | 2 | "5918133".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 14:12 |

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| S61 | 6 | higoshi.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 14:13 |
| S62 | 2649 | higashi.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 14:13 |
| S63 | 23 | "5918133" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 14:16 |
| S64 | 2 | "6682948".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 14:16 |
| S65 | 2 | "5918113".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 14:22 |
| S66 | 2 | "6304484".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 14:24 |
| S67 | 2 | "5753952".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 14:35 |
| S68 | 292 | hole near6 etch near6 electrode and @ad<="20000627" | US-PGPUB; USPAT; USOCR; DERWENT; IBM_TDB | OR | ON | 2005/03/25 16:50 |
| S69 | 298 | hole near6 etch near6 electrode and @ad<="20000627" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 16:51 |

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| S70 | 93 | hole near3 etch near3 electrode and @ad<="20000627" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 16:52 |
| S71 | 3 | etch adj through adj electrode | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 16:54 |
| S72 | 0 | etch adj hole adj electrode | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 16:54 |
| S73 | 53 | etch near2 hole near2 electrode | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/25 16:59 |
| S74 | 32 | etch near2 hole near2 electrode and @ad<="20000627" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/28 16:10 |
| S75 | 56 | etch near2 hole near3 electrode and @ad<="20000627" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/03/28 16:10 |